Tyrone Camarero Specifications

Tyrone

Camerero: SDI300A2N-28

Key Feature

Virtualization, Software-defined Storage, High Performance Computing, Cloud Computing, Enterprise Server

- Dual socket E2, Intel Xeon 6 6700 series processors with E-cores, Up to 144C/144T; Up to 108MB Cache per CPU, Supports up to 330W TDP CPUs (Air Cooled), Supports up to 330W TDP CPUs (Liquid Cooled)
- 32 DIMM slots supporting up to 2TB of memory
- Optional PCle slot configurations up to 8 PCle 5.0 x8 or 4 PCle 5.0 x16 slots with support for double-width GPU/Accelerator cards
- Flexible networking options with up to 2 AIOM networking slots (OCP NIC 3.0 compatible)
- 8x 2.5" hot-swap NVMe/SATA/SAS drive bays with optional configurations for 16x/24x 2.5" hot-swap NVMe/SAS/SATA drive bays; 2x internal M.2 NVMe drive slots; Optional RAID support via storage add-on card
- 4x 8cm heavy duty fans with optimal fan speed control, 2 Air Shroud(s), Direct to Chip (D2C) Cold Plate (optional)
- 2x 1200W Redundant (1 + 1) Titanium Level (96%) power supplies





Processor/Cache

Processor Dual socket E2, Intel Xeon 6 6700 series

processors with E-cores, Up to 144C/144T; Up to 108MB Cache per CPU, Supports up to 330W TDP CPUs (Air Cooled), Supports up to 330W TDP CPUs (Liquid Cooled)

Chipset

Chipset System on Chip

System Memory

Memory Capacity 32 DIMM slots, Max Memory (1DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM, Max Memory (2DPC): Up to 2TB 5200MT/s ECC DDR5 RDIMM

Expansion Slot

PCI-Express Option A: 4 PCIe 5.0 x16 FH/10.5""L

double-width slot(s), 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible), 1 PCIe 5.0 x8 AIOM slot(s) (OCP 3.0 compatible)

Option B: 8 PCIe 5.0 x8 (in x16) FH/10.5""L slot(s), 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible), 1 PCIe 5.0 x8 AIOM slot(s)

(OCP 3.0 compatible)

Integrated Onboard

USB 2 USB 3.0 port(s) (rear), 2 USB 3.0 port(s)

(Header)

LAN 1 RJ45 1 GbE Dedicated BMC LAN port(s)

Add-on Options

Raid Card Optional

Optical

Drive

None

Drive bays

HDD Bays 8 front hot-swap 2.5""

NVMe*/SAS*/SATA* drive bay(s) **Option A:** Total 16 bay(s), 16 front
hot-swap 2.5"" NVMe*/SAS*/SATA*

drive bay(s)

Option B: Total 24 bay(s), 24 front hot-swap 2.5" NVMe*/SAS*/SATA*

drive bay(s)

Power Supply

Power Supply 2x 1200W/2000W/1600W/2600W

Redundant (1 + 1) Titanium Level (96%)

power supplies

Cooling System

4x 8cm heavy duty fans with optimal fan speed control

Form Factor

Form Factor 2U Rackmount

Email: Info@tyronesystems.com
For more/current product information, Visit
www.tyronesystems.com

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